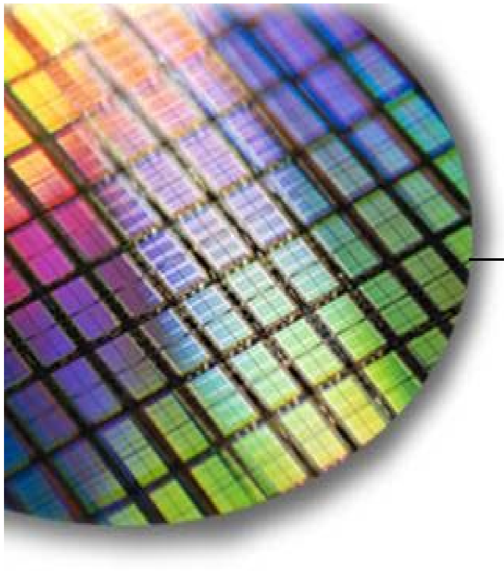


The World Leader in High Performance Signal Processing Solutions

AD5535B Burn In Removal

ANALOG DEVICES

ADI Confidential Information – *Not for external distribution*

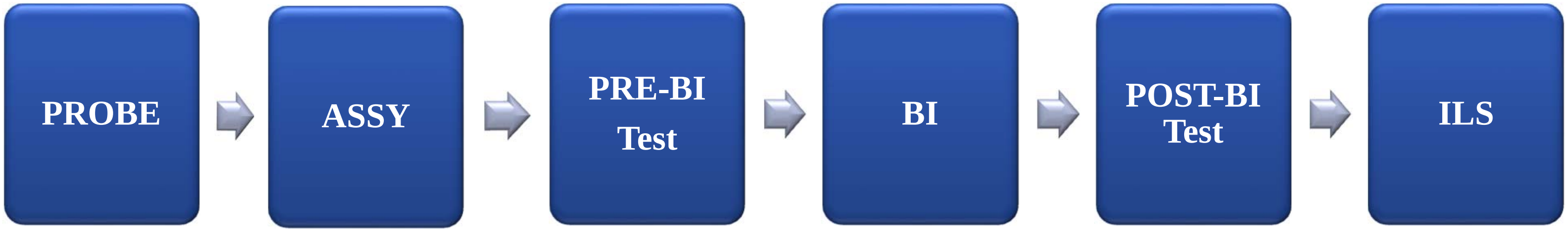
AD5535B Burn-In Removal Data

- **Overview**
  - **Production Burn-in was introduced post release to gather additional wafer fab process Reliability Monitor data**
  - **Analysis of Reliability Data was completed and warrants removal of Burn-in**
  - **No changes on Test Coverage**

- **Data Analysis (Burn-in Results)**
  - **Sample size: 4,900**
  - **Result:**
    - Zero Burn-in failures
    - No Parametric Shift observed

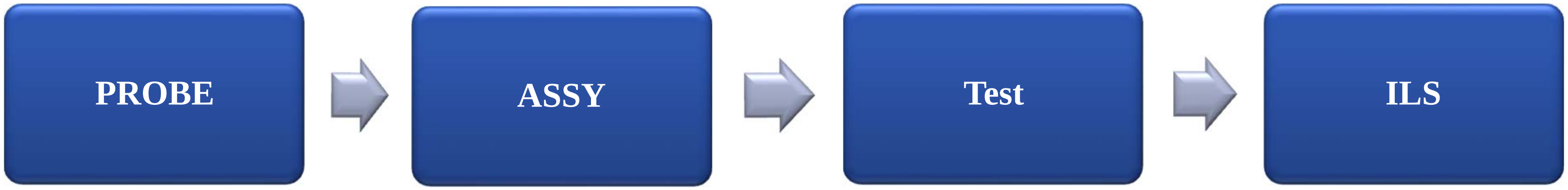
Production Test Flow Changes

- **Current Production Test Flow.**



PROBE → ASSY → PRE-BI Test → BI → POST-BI Test → ILS

- **Proposed Production Test Flow.**



PROBE → ASSY → Test → ILS